

DIP - TEST CLIPS

DIP CLIP™

Emulation Technology test adapters are designed especially for testing dual-in-line IC packages on high-density PC boards. The DIP CLIP™ test adapter has many built-in features that assure a positive electrical connection while providing hands-free testing.

The high density DIP CLIP™ test adapters are used for ultra-dense packaged chips located adjacent to each other on 2.54mm (.100") spacing.

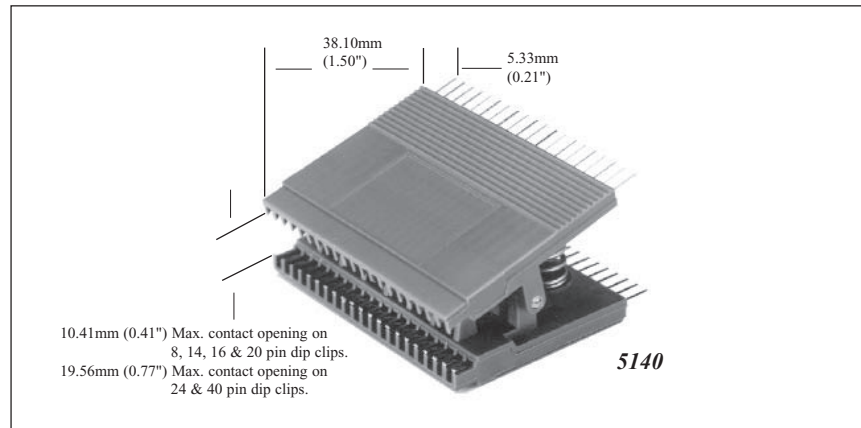
MATERIAL: Contact, tarnish resistant Nickel, Silver or Gold plated Beryllium Copper. Stainless steel hinge pin and spring.

INSULATION: Glass filled nylon, blue.

RATING: 500 VRMS; 1 Amp; +102°C (+126°F) Max.

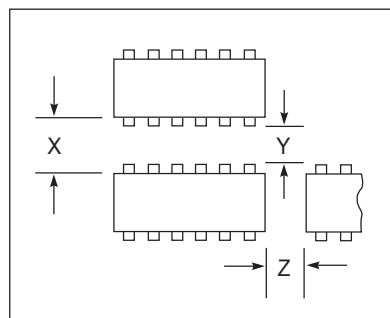
FEATURES

- Contacts 1.02 mm (.040") wide on lower end are serrated for good electrical connection
- 0.64mm (.025")X0.71mm (.028") square serrated test points on upper end will accept wire wraps or mini test clips
- Molded barrier between each contact allows connections to be made on live boards without accidental shorting of adjacent contacts



Part #	No. of Pins	Contact Material	Type
5108	8	Gold Plated Beryllium Copper	Standard
5208	8	Gold Plated Beryllium Copper	High Density
5014	14	Spring Tempered Nickel Silver	Standard
5114	14	Spring Tempered Nickel Silver	High Density
5214	14	Gold Plated Beryllium Copper	Standard
5314	14	Gold Plated Beryllium Copper	High Density
3916A	16	Spring Tempered Nickel Silver	Standard
4236A	16	Spring Tempered Nickel Silver	High Density
5116	16	Gold Plated Beryllium Copper	Standard
5216	16	Gold Plated Beryllium Copper	High Density
5120	20	Gold Plated Beryllium Copper	Standard
5220	20	Gold Plated Beryllium Copper	High Density
4124A	24	Spring Tempered Nickel Silver	Standard*
4324A	24	Spring Tempered Nickel Silver	High Density*
5124	24	Gold Plated Beryllium Copper	Standard*
5224	24	Gold Plated Beryllium Copper	High Density*
4140A	40	Spring Tempered Nickel Silver	Standard*
4340A	40	Spring Tempered Nickel Silver	High Density*
5140	40	Gold Plated Beryllium Copper	Standard*
5240	40	Gold Plated Beryllium Copper	High Density*

*For .600 MIL DIP Only.



	X Min.	Y Min.	Z Min.
Single Chip Testing Standard	3.30mm (.130")	1.91mm (.075")	1.02mm (.040")
Single Chip Testing High Density	2.67mm (.105")	1.27mm (.050")	1.02mm (.040")
Adjacent	7.62mm (.300")	5.72mm (.225")	2.03mm (.080")

For a complete test clip listing, pricing and delivery information, please see
Web Link: www.1800adapter.com/040